IPC ASSOCIATION ELECTRONIC	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights results international and Pan-American copyright conventions.		ll rights reserved unations.	der both	This document is a declaration of the substances within the manulevel parts, the declaration encompasses all lower level materials				within the manufacturer level materials for w	rer listed i	tem. Note: nanufacture	if the item is an as er has engineering	sembly with lowe responsibility.	
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and M	fg Informa	tion				
Supplie	r Information														
Company name*				ompany unique ID			Unique ID Authority				Respons	Response Date*			
onsemi										2025-06	2025-06-06				
Contact N	lame	Title - Contact			1	Phone - Contact*				Email -	Email - Contact*				
Product-l	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorize	ed Representative*	Title - Representative			I	Phone - Representative*				Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number		fr Item Number Mfr Item Name			Effectiv		te Versio	on]	Manufacturing Site		Weight*	UOM	Unit Type	
		NRVUB	1620CTRT4G	REC ULTRAFAST	Γ RECTIFIEF	₹	2025-06-06		1	MY1		1420.1	mg	Each	
Aanufa	cturing Process Informa														
	Terminal Plating / Grid Array Material Terminal Base A						1	Peak Process Body Temperature Max Time at Peak			Temperature Number of Reflow Cycles				
	Matte Tin (Sn) - annealed	C	CU Alloy	1			260		C	30	secon	ds 3			
omments															
vel 1 - m	aximum time at peak temperat	ture during sol	dering is 10-3	0 seconds											
or more	information regarding materia	l composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		by mass (100 PPM) in homogeneous material for tum (Cr6+), Polybrominated Biphenyls (PBB), Polyl Disobutyl phthalate (DIBP).								
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier prov										
RoHS Declaration * 4 - Item(s	s) does not contain RoHS restricted substance	ces per the definition above except for selected exer	nptions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead). Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature R		,								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.19	mg	Supplier	Silicon (Si)	7440-21-3		0.1881	mg
			Supplier	Lead Bisilicate	65997-18-4	7c	0.0019	mg
Die Attach	11.34	mg	A	Lead (Pb)	7439-92-1	7a	10.773	mg
			Supplier	Tin (Sn)	7440-31-5		0.567	mg
Lead Frame	851.91	mg	В	Nickel (Ni)	7440-02-0		2.5557	mg
			Supplier	Copper (Cu)	7440-50-8		849.3542	mg
Mold Compound-Black	529.31	mg		Epoxy resin	proprietary data		37.0517	mg
			Supplier	Phenolic Resin	Proprietary Data		15.8793	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		52.931	mg
			Supplier	Carbon Black (C)	1333-86-4		2.6465	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		420.8015	mg
Plating	27.15	mg	Supplier	Tin (Sn)	7440-31-5		27.15	mg
Wire Bond - Al	0.2	mg	Supplier	Aluminum (Al)	7429-90-5		0.2	mg